

A

B

C

D

A

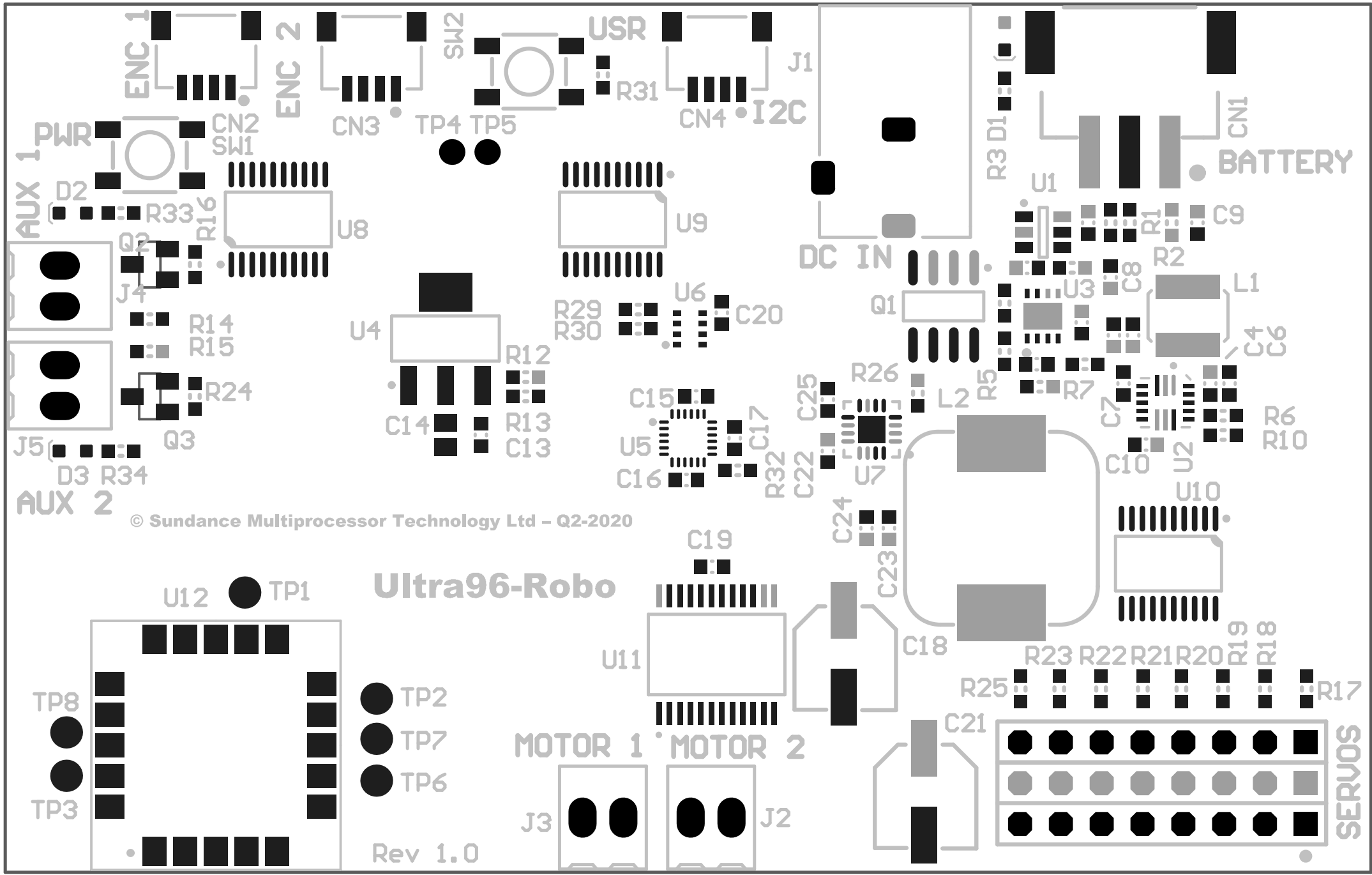
B

C

D

FABRICATION CHART

Circuit Type	Copper Weight	Layer Count
<input type="checkbox"/> PTH	<input checked="" type="checkbox"/> 1oz <35um>	<input type="checkbox"/> 2 Layer
<input type="checkbox"/> SMD	<input type="checkbox"/> 2oz <71um>	<input checked="" type="checkbox"/> 4 Layer
<input checked="" type="checkbox"/> Both	<input type="checkbox"/> Other _____	<input type="checkbox"/> Other _____
Surface Finish	Finish Thickness	Core Thickness
<input checked="" type="checkbox"/> HASL(pB free)	<input type="checkbox"/> 2.0um (min)	<input type="checkbox"/> 1.0mm
<input type="checkbox"/> Gold Flash	<input checked="" type="checkbox"/> 3.0um (min)	<input checked="" type="checkbox"/> 1.6mm
<input type="checkbox"/> Other _____	<input type="checkbox"/> Other _____	<input type="checkbox"/> Other _____
Track Thickness	Copper Clearance	CTI Rating
<input type="checkbox"/> 0.1mm (min)	<input type="checkbox"/> 0.1mm (min)	<input type="checkbox"/> CTI>=600
<input type="checkbox"/> 0.15mm(min)	<input type="checkbox"/> 0.15mm(min)	<input type="checkbox"/> 600>CTI>400
<input checked="" type="checkbox"/> 0.2mm (min)	<input checked="" type="checkbox"/> 0.2mm (min)	<input type="checkbox"/> 400>CTI>250
<input type="checkbox"/> Other _____	<input type="checkbox"/> Other _____	<input checked="" type="checkbox"/> CTI>=175

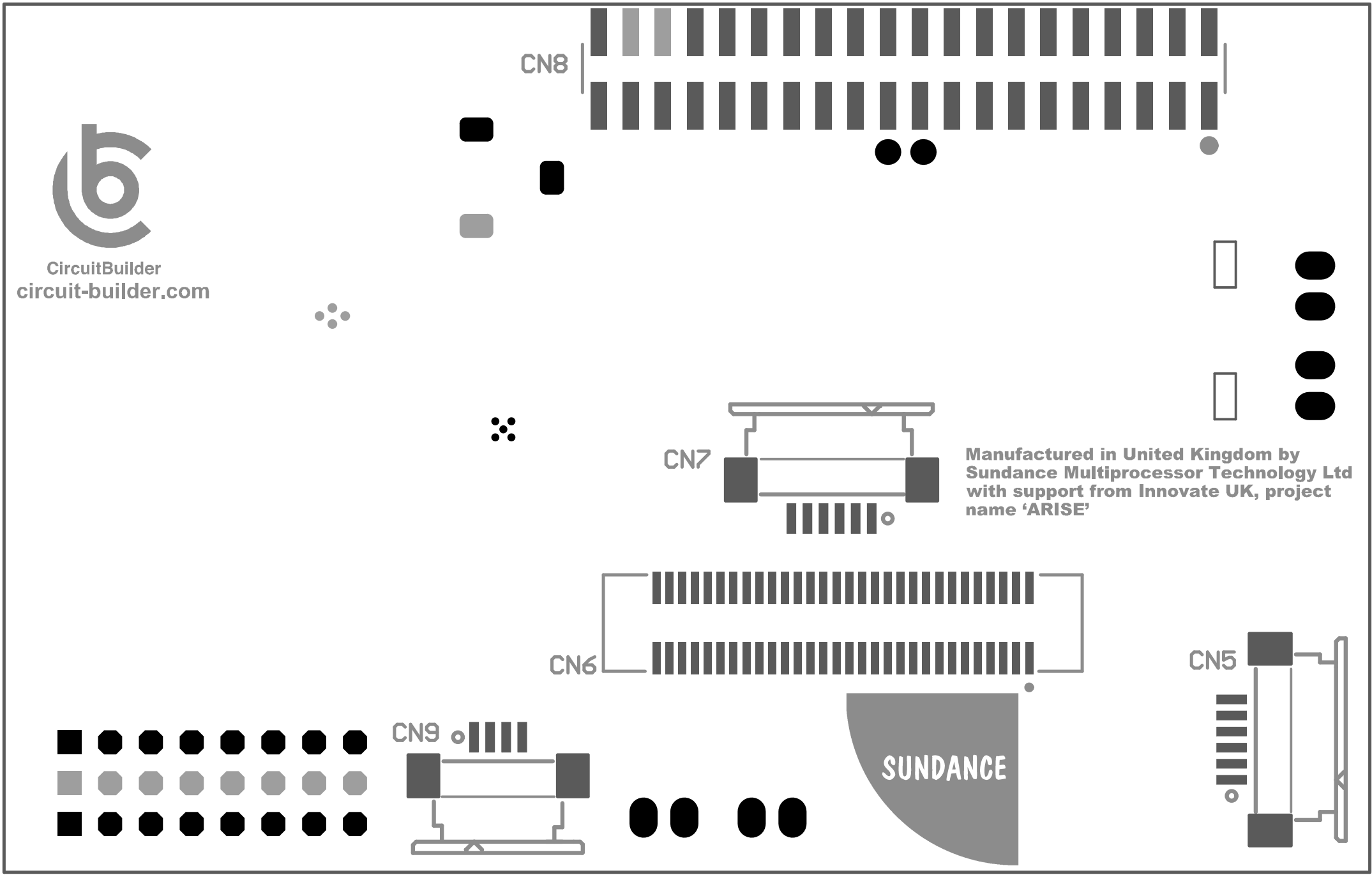


NOTES - (UNLESS OTHERWISE SPECIFIED)

- * Base Material Glass Fibre Epoxy Resin Nema Grade FR4
- * Hole Sizes Drill Diameters shown are finished sizes after plating
- * Plating For 1oz copper board hole plating must be 0.5oz copper thickness min
- * Standards PCB shall meet UL-796, UL94V-0, RoHS compliant.
- * Bow & Twist Maximum PCB bow & twist to be 0.75%
- * Changes No Dimensional, Material or Process changes are allowed without explicit prior written permission from CircuitBuilder
- * Material Tolerance Core material thickness to be 1.6mm +/- 0.2mm
- * Colours Green solder resist, white silkscreen

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric 1	FR-4	0.185mm	4.2	
5	Internal Plane 2	Copper	0.035mm		
6	Dielectric 3		1.150mm	4.2	
7	Signal Layer 1	Copper	0.035mm		
8	Dielectric 2		0.185mm	4.2	
9	Bottom Layer	Copper	0.035mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

ENGINEER:	Ultr a96-Robo		
PCB DESIGNER: AT			
DATE: 16/04/2020	PART NO.:	REV: 1.0	
FILE NAME: Ultra96 Robotics Board.PcbDoc	DWG NO:	SCALE:	



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